

BOARD CHARACTERISTICS

Copper Layer Count: 4

Board overall dimensions: 160.0000 mm x 100.0000 mm

Min track/spacing: 0.1200 mm / 0.1300 mm

Copper Finish: Immersion gold

Castellated pads: No

Edge card connectors: No

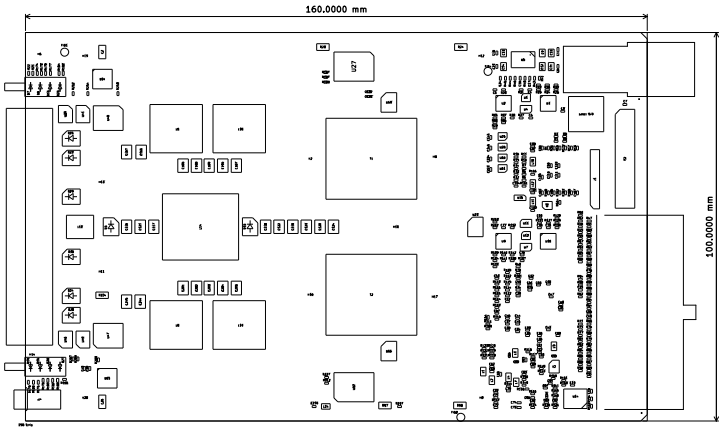
Board Thickness: 1.5820 mm

Min hole diameter: 0.3000 mm

Impedance Control: No

Plated Board Edge: No

Layer Name	Type	Material	Thickness (mm)	Color	Epsilon R	Loss Tangent
F.Silkscreen	Top Silk Screen	Not specified	0 mm	Not specified	1	0
F.Paste	Top Solder Paste	Not specified	0 mm	Not specified	1	0
F.Mask	Top Solder Mask	Not specified	0.01 mm	Not specified	3.5	0
F.Cu	copper	Not specified	0.035 mm	Not specified	1	0
Dielectric 1	prepreg	1080	0.14 mm	FR4 natural	3.95	0.02
in1.Cu	copper	Not specified	0.035 mm	Not specified	1	0
Dielectric 2	core	FR4	1.1 mm	Not specified	4.6	0.02
in2.Cu	copper	Not specified	0.035 mm	Not specified	1	0
Dielectric 3	prepreg	1080	0.14 mm	Not specified	3.95	0.02
B.Cu	copper	Not specified	0.035 mm	Not specified	1	0
B.Mask	Bottom Solder Mask	Not specified	0.01 mm	Not specified	3.5	0
B.Paste	Bottom Solder Paste	Not specified	0 mm	Not specified	1	0
B.Silkscreen	Bottom Silk Screen	Not specified	0 mm	Not specified	1	0



File: cq2.kicad.pcb		
Sheet: KICad.kicad.pcb		
Function:	Product: CQ2	Layout Revision: 0.00
Designed by:	Design Date:	Page Revision:
Reviewed by:	Review Date:	
KICad E.D.A. 8.0.4	Issue Date: 2024-07-29	Size: A3 Page: 1/1